

MODEL: HSB33-272710 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- low profile
- aluminum alloy
- black anodized finish



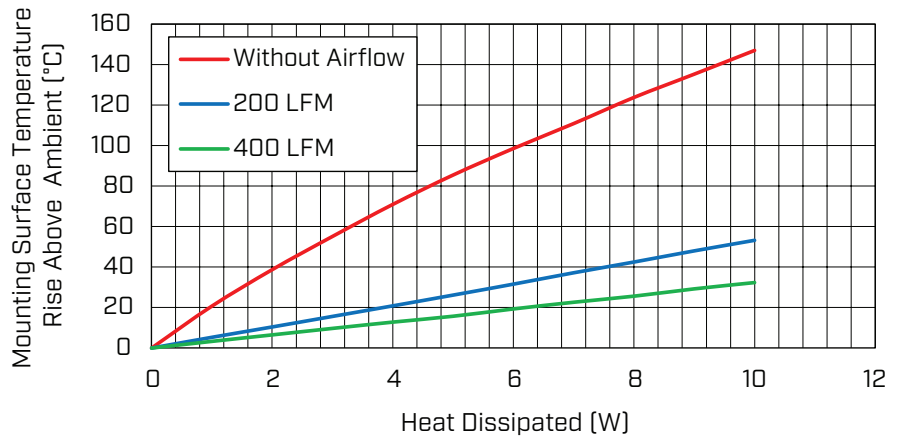
MODEL

	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	
HSB33-272710	17.22	20.7	5.3	3.3	4.36

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	20.7	5.3	3.3
2	38.7	10.4	6.5
3	55.1	15.6	9.7
4	70.9	20.8	12.8
5	85.4	26.1	15.7
6	98.5	31.5	19.3
7	110.8	37.1	22.6
8	123.7	42.4	25.6
9	135.2	47.9	29.2
10	146.9	53.1	32.3

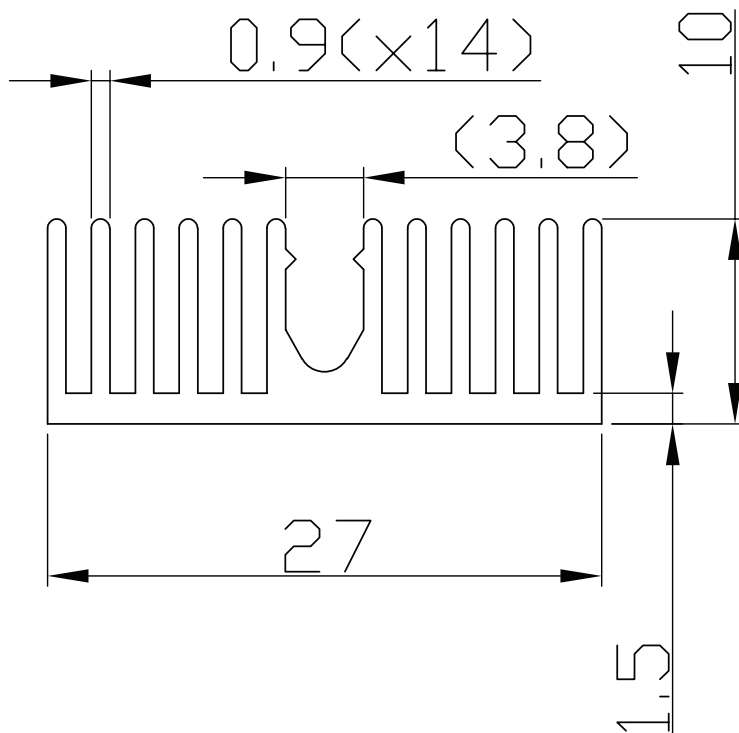
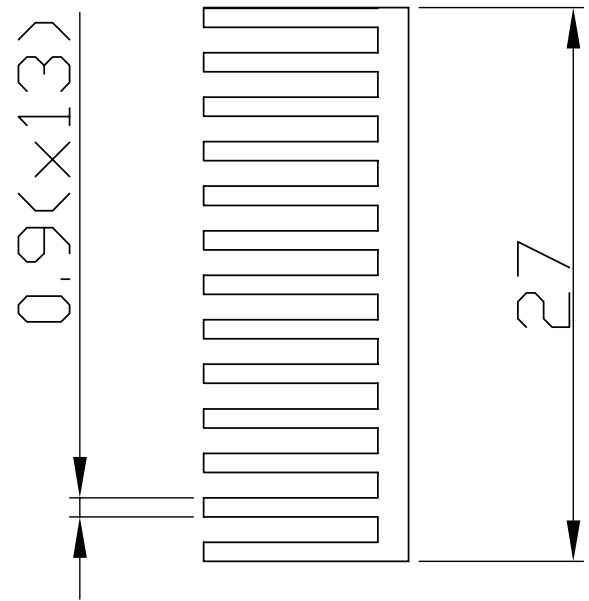
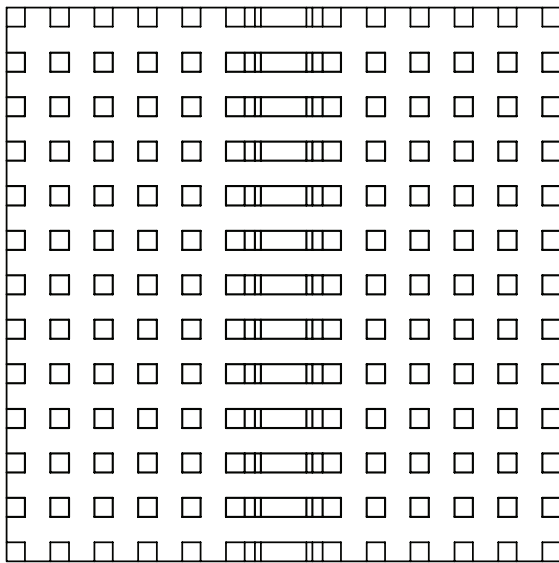


T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ±0.50 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	6 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/01/2024

The revision history provided is for informational purposes only and is believed to be accurate.



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